



## Material Content Data Sheet



Sales Product Name	TLE7231G			Issued		3. July 2019		
MA#	MA005344682							
Package	PG-DSO-14-1			Weight*		143.38 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.214	2.24	2.24	22417	22417
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.01		105	
	non noble metal	zinc	7440-66-6	0.060	0.04		421	
	non noble metal	iron	7439-89-6	1.207	0.84		8418	
	non noble metal	copper	7440-50-8	49.007	34.18	35.07	341808	350752
wire	noble metal	gold	7440-57-5	0.403	0.28	0.28	2808	2808
encapsulation	organic material	carbon black	1333-86-4	0.171	0.12		1196	
	plastics	epoxy resin	-	7.887	5.50		55010	
	inorganic material	silicondioxide	60676-86-0	77.671	54.17	59.79	541728	597934
leadfinish	non noble metal	tin	7440-31-5	1.226	0.86	0.86	8552	8552
plating	noble metal	silver	7440-22-4	1.030	0.72	0.72	7182	7182
glue	plastics	acrylic resin	-	0.327	0.23		2278	
	noble metal	silver	7440-22-4	1.158	0.81	1.04	8077	10355
*deviation	< 10%	Sum in total:				100.00		1000000

### Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com